

*Paragon Semiconductor Lighting Technology*

*PSLT*

**ParagonLED**

## Specifications

**Product Type : ParaLED-A-084230V-12W3000A-BB**

**Issued Date : 12/01/2015**

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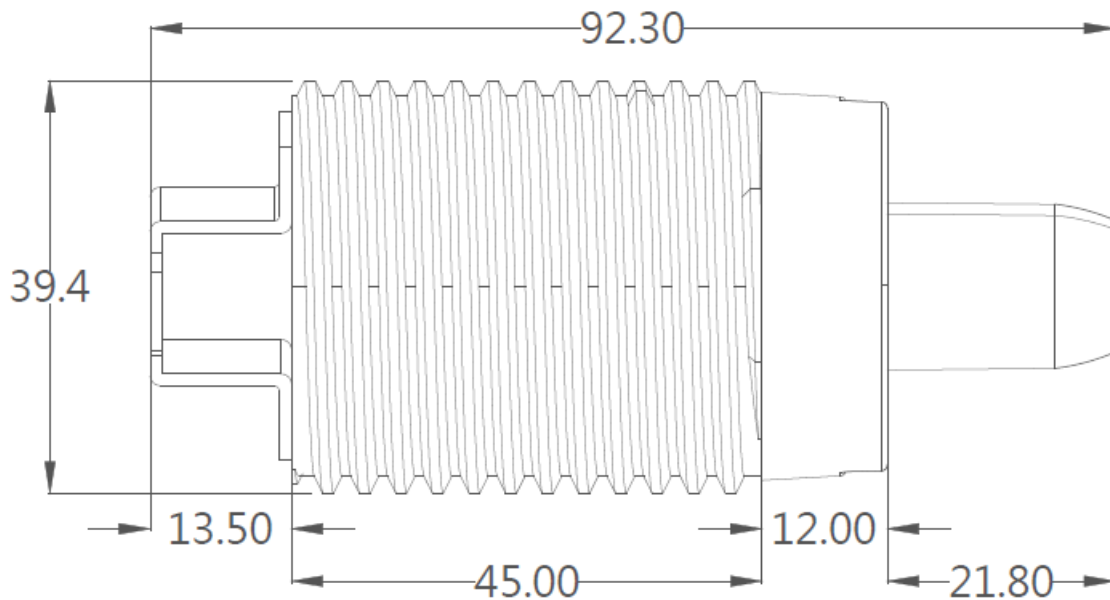
# 1.General Description

## (1)Naming rule

**ParaLED-A-084-230V12W3000A-BB**

- Product Series type : ParaLED
- Dimming Type : Dimmable
- Numbers of chips on board : 84
- Voltage : 230VAC
- Power Dissipation : 12W
- Color Temperature : 3000K
- Color Rendering : >RA90
- Appearance : Fixing Iron piece(13.5mm) + socket(45mm)
- Optical parts : Light Guide Lens

## (2)Outline Dimensions (Unit : mm / Tolerance: 0.2mm)



## 2. Electro-Optical Characteristics

### (1) Absolute Maximum Rating

| Parameter                    | Symbol    | Value           | Unit |
|------------------------------|-----------|-----------------|------|
| Power Dissipation            | $P_D$     | 12              | W    |
| Forward Voltage              | $V_F$     | 230             | V    |
| Operating Temperature        | $T_{opr}$ | -40 ~ +105      | °C   |
| Storage Temperature          | $T_{stg}$ | -40 ~ +105      | °C   |
| Power Factor                 | Pf        | >0.95           |      |
| THDi                         |           | <20%            |      |
| Dimming                      |           | available       |      |
| Assembly process temperature | $T_{sol}$ | <325°C , 5 secs |      |

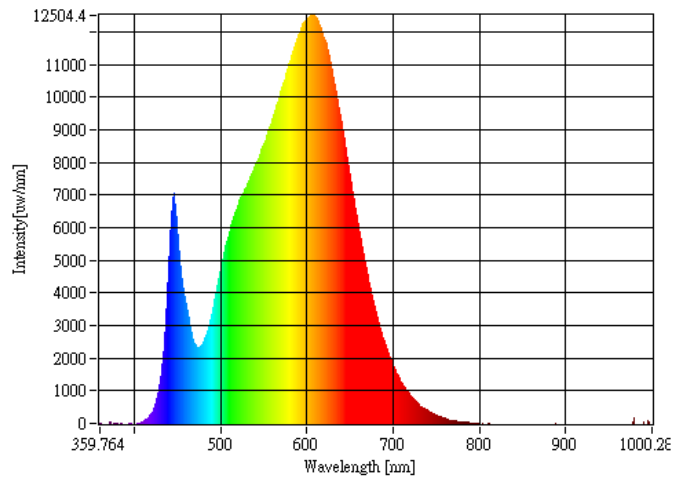
### (2) Electro-Optical Characteristics

| Parameter          | Symbol   | Condition  | Min | Typ | Max | Unit |
|--------------------|----------|------------|-----|-----|-----|------|
| Forward Voltage    | $V_F$    | -          | -   | 230 | -   | V    |
| Luminous Intensity | $\Phi_v$ | $V_F=230V$ | -   | 660 | -   | Lm   |
| Color rendering    | Ra       | $V_F=230V$ | 90  | -   | -   | CRI  |

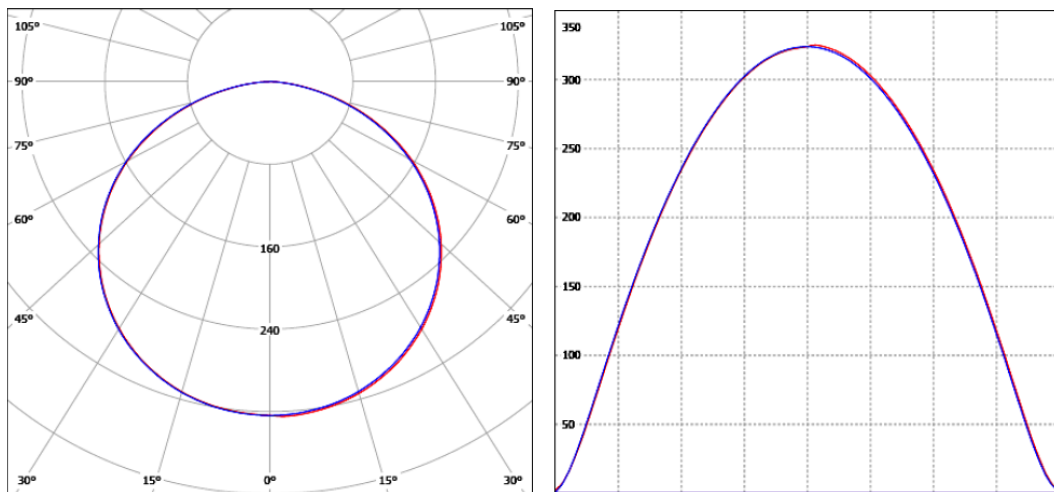
**Notice: Operating Voltage of product varies from 220V~240V · users must keep the temperature of solder joint point under 105 °C (with suitable heat sink), or may cause Serious luminous decay. We DO NOT guarantee of improper use.**

### (3) Graphs

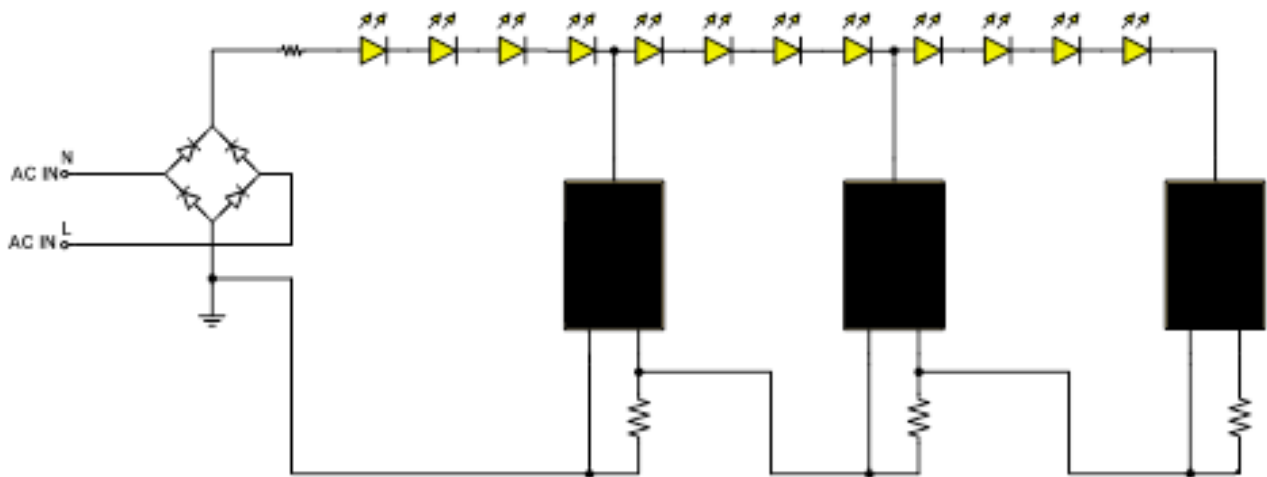
#### Spectrum



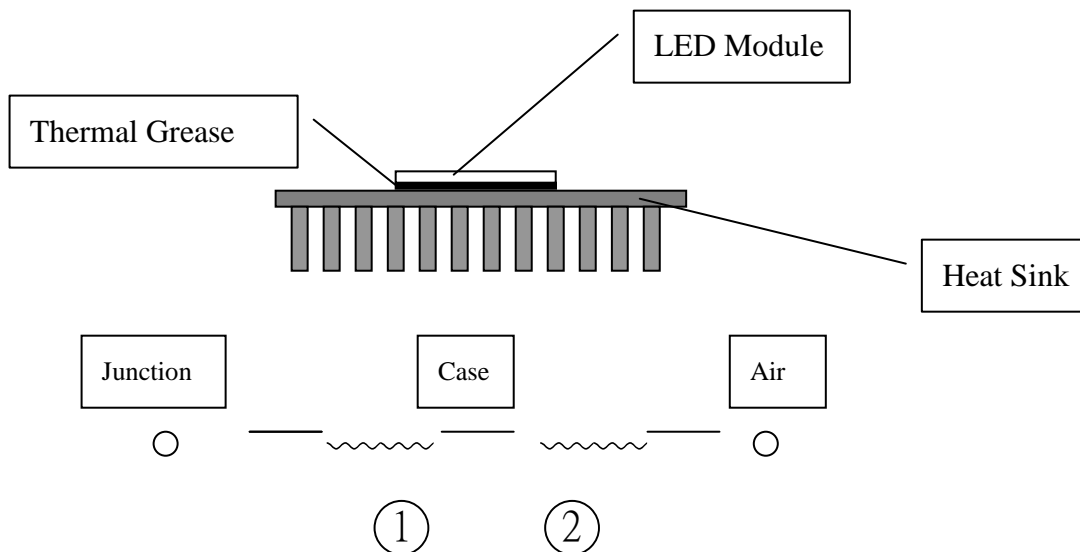
#### Candle Power Distribution & Cartesian Coordinate



### (4) Layout



### 3. Junction Temperature Measurement



- ① Thermal resistance of Junction to Case without heat sink :  $10^{\circ}\text{C}/\text{W}$  [ Reference Value ]
- ② Thermal resistance of Case to Ambient Air: Depending on what kind of heat sink users choose. In ideal thermal dissipation situation, the thermal resistance is about  $1\sim 2^{\circ}\text{C}/\text{W}$ .

### 4. Reliability Test

| Test Item                     | Test Conditions   | Number of failed |
|-------------------------------|---|------------------|
| High Temperature Storage Test | $T_{\text{stg}} = +80^{\circ}\text{C}$ , x1,000 hrs                         | 0/20             |
| Low Temperature Storage Test  | $T_{\text{stg}} = -40^{\circ}\text{C}$ , x1,000 hrs                         | 0/20             |
| Continous Light-on Test       | $T_{\text{a}} = 25^{\circ}\text{C}$ , RH=65%, x1,000 hrs                    | 0/20             |
| Boiling Test                  | $T_{\text{a}} = 100^{\circ}\text{C}$ , RH=100%, x180mins                    | 0/20             |
| Thermal Cycle Test            | $-40^{\circ}\text{C}$ x 30 mins, $80^{\circ}\text{C}$ x 30 mins, 100 cycles | 0/20             |

| Measuring Item      | Measuring Condition          | Judging Criteria of Failure |
|---------------------|------------------------------|-----------------------------|
| Forward Voltage     | $I_{\text{F}} = 230\text{V}$ | $> 0 \times 1.1$            |
| Total Luminous Flux | $I_{\text{F}} = 230\text{V}$ | $< L \times 0.7$            |